

CALL FOR PAPERS



68th ECTC



ELECTRONIC COMPONENTS AND TECHNOLOGY CONFERENCE

May 29 – June 1, 2018
Sheraton San Diego Hotel & Marina
San Diego California, USA

OPTOELECTRONICS COMMITTEE

Papers are solicited on all topics pertaining to the design, development, and technology of packaging active/passive, hybrid, integrated and nano scale photonic components, devices, circuitry and systems

Topics of interest include:

- **Optical Components for Computer-Com:** Dense low-cost parallel optical transceivers; optical engines; co-packaging of mid-board / on-board optical modules; parallel fiber and waveguide optical coupling; massively parallel optical interconnects; board-level waveguides; optical backplanes; glass/polymer low cost optics/waveguides; embedded optics; single mode and multicore fibers and high-density optical engines; photonic interposer.
- **Silicon Photonics Packaging and Integration:** Monolithic and hybrid packaging of photonic integrated circuits; hybrid lasers; high-speed performance; energy efficiency of packages; micro-nano optical interconnects; assembly, processing, testing, characterization, reliability, thermal management; photonic/electronic hybrid cointegration; fiber to PIC coupling
- **Nano-Optics:** Optical and physical properties; nano- and meta-materials; integration of nano- and conventional materials; high-efficiency lasers; advanced packaging, assembly, test and reliability
- **High-Efficiency LEDs and High Power Lasers:** Package and optical design; assembly methods and automation; thermal management, reliability and aging effects; color temperature control; optimization of phosphor and QD converters; μ -LED packaging; volume manufacturing; laser integration for 3D packaging; high-power laser diodes, bars/stacks; fiber coupled modules; high-power VCSELs and fiber lasers packaging technologies including pump diodes, beam combining, coupling, wavelength control; Monolithic and Hybrid integration of LEDs with drivers and ASIC; μ -LED arrays
- **Optical Sensor Packaging:** On-chip and packaged biological, chemical, pressure, temperature, humidity sensors; integrated spectrometer; MEMS sensors; sensor assembly utilizing optical fibers, waveguides, and free-space micro-optics
- **Micro-optical System Integration and Photonic System-in-Package Technologies:** Heterogeneous and 3D photonics integration; silicon and glass based interposer; optical vias; integrated optics; fiber optic connectors and hybrid integration; nano-photonics packaging; novel interconnection technology and efficient coupling approaches
- **Photonic Packaging & Manufacturing Technologies:** Wafer-scale processing and fabrication; photonic panel level packaging; low cost designs and cost reduction techniques; novel micro-optics, assembly methodology; precision assembly of optical components and automation technology; substrates and housing; testing and reliability; advanced thermal management

You are invited to submit a 750-word abstract via the ECTC Website <http://www.ectc.net>

Abstract On-Line Submission opens **August, 2017**; Abstracts Due: **October 9, 2017**

(PLEASE SELECT **OPTOELECTRONICS** AS YOUR **PRIMARY COMMITTEE** FOR SUBMISSION)

(You may also submit directly to the committee chairs below – please include mailing address, telephone number, FAX number and e-mail):

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